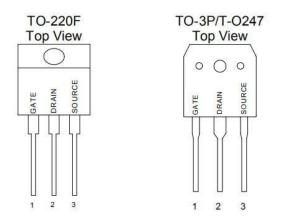


GENERAL DESCRIPTION

This high voltage MOSFET uses an advanced termination scheme to provide enhanced voltage-blocking capability without degrading performance over time. In addition, this advanced MOSFET is designed to withstand high energy in avalanche and commutation modes. The new energy efficient design also offers a drain-to-source diode with a fast recovery time. Designed for high voltage, high speed switching applications in power supplies, converters and PWM motor controls, these devices are particularly well suited for bridge circuits where diode speed and commutating safe operating areas are critical and offer additional and safety margin against unexpected voltage transients.

PIN CONFIGURATION

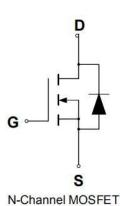


ABSOLUTE MAXIMUM RATINGS

FEATURES

- **Robust High Voltage Termination**
- Avalanche Energy Specified
- Source-to-Drain Diode Recovery Time Comparable to a **Discrete Fast Recovery Diode**
- Diode is Characterized for Use in Bridge Circuits
- I_{DSS} and V_{DS}(on) Specified at Elevated Temperature
- Isolated Mounting Hole Reduces Mounting Hardware

SYMBOL



Rating

19.4 58.3 ±20 42 245 403 0.33 1.96	A V W W C
±20 42 245 403 0.33	W
42 245 403 0.33	W
245 403 0.33	
403 0.33	₩/° C
0.33	W/°C
	W/°C
1.96	
3.23	
-55 to 150	°C
720	mJ
3	°C/W
0.51	
0.31	
62.5	
40	
260	°C
	 -55 to 150 720 3 0.51 0.31 62.5 40

(1) Drain current limited by maximum junction temperature



ORDERING INFORMATION

Part Number	TOP MARK	Part Number	Packing Mthod	Note
GWM19S80N220FP(Note1)	GWM19S80X	TO-220FP	Tube	
GWM19S80N3P(Note1)	GWM19S80X	TO-3P	Tube	
GWM19S80N247(Note1)	GWM19S80X	TO-247	Tube	

Note1: X : Suffix for Halogen Free Product.

ELECTRICAL CHARACTERISTICS

Unless otherwise specified, T_J = 25 $^\circ\!\mathrm{C}$.

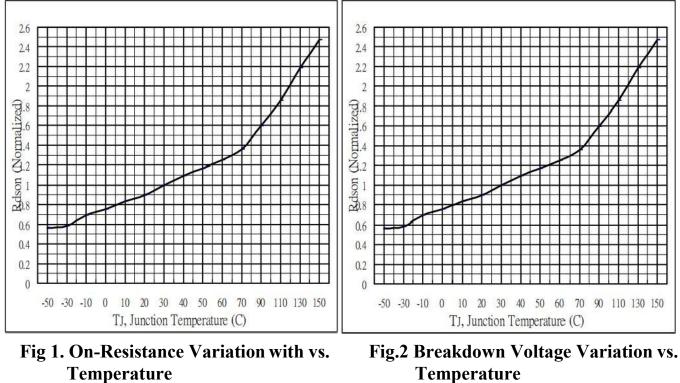
			GWM19S80			
Cha	Symbol	Min	Тур	Max	Units	
Drain-Source Breakdown Voltage (V _{GS} = 0 V, I _D = 250 μ A)		V _{(BR)DSS}	800			V
Drain-Source Leakage Current		I _{DSS}			1	uA
$(V_{DS} = 800 \text{ V}, V_{GS} = 0 \text{ V})$						
Gate-Source Leakage Current-Forward (V_{qsf} = 20 V, V_{DS} = 0 V)		I _{GSSF}			100	nA
Gate-Source Leakage Current-Reverse $(V_{gsr} = -20 \text{ V}, V_{DS} = 0 \text{ V})$		I _{GSSR}			100	nA
Gate Threshold Voltage		V _{GS(th)}	2	3	4	V
$(V_{DS} = V_{GS}, I_D = 250 \ \mu A)$						
Static Drain-Source On-Resistance (V _{GS} = 10 V, I _D = 6.3A) *		R _{DS(on)}		220	260	mΩ
Input Capacitance	(V _{DS} = 25 V, V _{GS} = 0 V, f = 1.0 MHz)	Ciss		3384.0		pF
Output Capacitance		C _{oss}		203.0		pF
Reverse Transfer Capacitance		C _{rss}		50.0		pF
Turn-On Delay Time	$(V_{DD} = 300 \text{ V}, I_D = 19 \text{ A}, R_G = 25\Omega) *$	t _{d(on)}		40.6		ns
Rise Time		tr		69.8		ns
Turn-Off Delay Time		t _{d(off)}		101.6		ns
Fall Time		t _f		68.4		ns
Total Gate Charge		Qg		74.42		nC
Gate-Source Charge	$(V_{DS} = 480 \text{ V}, I_D = 19 \text{ A}, V_{GS} = 10 \text{ V})^*$	Q _{gs}		19.4		nC
Gate-Drain Charge	$v_{GS} = 10 v_j$	Q _{gd}		28		nC
	SOURCE-DRAIN DIODE CH	ARACTERISTICS				
Forward On-Voltage(1)	(1 - 10)	V _{SD}			1.5	V
Forward Turn-On Time	(I _s = 19 A, d _{Is} /d _t = 100A/µs)	t _{on}		**		ns
Reverse Recovery Time		trr		522.8		ns

* Pulse Test: Pulse Width ${\leq}300\mu\text{s},$ Duty Cycle ${\leq}2\%$

** Negligible, Dominated by circuit inductance



TYPICAL ELECTRICAL CHARACTERISTICS



100 ID, Drain-to-Source current [A] 61 10 1 AV 0.1 0.01 20us PULSE WIDTH. TI=250 T 0.001 0.01 0.1 1 10 100 VDs, Drain-to-Source Voltage [V]

Fig 3. Typical Output Characteristics

Temperature

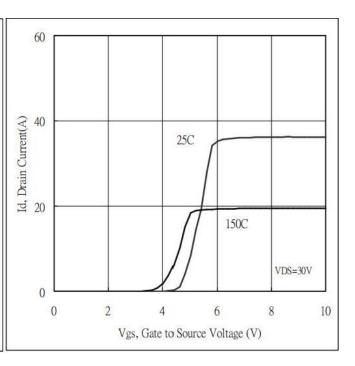


Fig 4. Typical Transfer Characteristics